

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC9250xxxxQR-G
Typical Mass: 80 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	2.378	Silicon	29700	7440-21-3
	-	Arsenic	<1	7440-38-2
Leadframe	26.731	Copper	334100	7440-50-8
	0.358	Iron	4500	7439-89-6
	0.019	Zinc	200	7440-66-6
	0.013	Phosphorus	200	7723-14-0
	0.219	Silver	2700	7440-22-4
Die attach	0.414	Silver	5200	7440-22-4
	0.054	Epoxy resin	700	—
	0.004	Phenol resin	100	—
Bonding wire	0.255	Gold	3200	7440-57-5
Resin	42.957	Silica	537000	60676-86-0
	3.852	Epoxy resin	48100	—
	0.837	Phenol resin	10500	—
	0.586	Silica (crystal)	7300	14808-60-7
Plating	1.321	Tin	16500	7440-31-5

* The component composition is based on the information provided by raw material vendor.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."